19-2307; Rev 1; 7/95

μP Compatible CMOS 14-Bit D/A Converter

General Description

The Maxim MX7538 is a high performance monolithic 14-bit multiplying digital-to-analog converter (DAC).

The MX7538 operates with a 14-bit data bus using standard chip select and memory write logic. A Load DAC (LDAC) signal is provided where double buffering is required, such as in systems with multiple DACs. If the LDAC signal is kept low, the DAC register becomes transparent. The MX7538 is optimized for unipolar applications, but can be operated as a bipolar DAC with additional external components.

Full accuracy is maintained over the operating temperature range through the use of wafer-level laser-trimmed, thin-film resistors and temperature compensated NMOS switches. In addition, all digital inputs are compatible with both TTL, 74HC and 5V CMOS logic levels.

The MX7538 is available in the narrow (0.3") 24-lead DIP and Wide SO (0.3") packages.

Applications

Machine and Motion Control Systems Automatic Test Equipment **Digital Audio Synthesis** μP Controlled Calibration Circuitry **Programmable Gain Amplifiers Digitally Controlled Filters**

Programmable Power Supplies

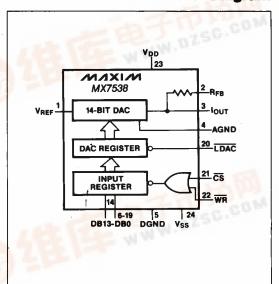
Feetures 14-Bit Monotonic Over Full Temperature Range

- 4-Quadrant Multiplication
- μP Compatible Double Buffered Inputs
- **Low Power Consumption**
- TTL, 74HC and 5V CMOS Compatible
- **Low Output Leakage Over Temperature Range**
- Small 24-Lead 0.3" DIP or Wide SO Packages

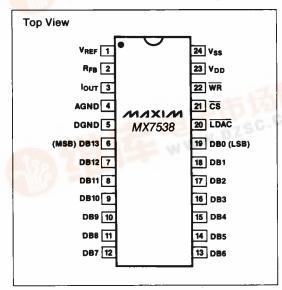
Ordering Information

PART	TEMP. RANGE	PACKAGE*	ERROR
MX7538JN	0°C to +70°C	Plastic DIP	±2 LSB
MX7538KN	0°C to +70°C	Plastic DIP	±1 LSB
MX7538JCWG	0°C to +70°C	Wide SO	±2 LSB
MX7538KCWG	0°C to +70°C	Wide SO	±1 LSB
MX7538JP	0°C to +70°C	PLCC	±2 LSB
MX7538KP	0°C to +70°C	PLCC	±1 LSB
MX7538J/D	0°C to +70°C	Dice	±2 LSB
MX7538JEWG	-40°C to +85°C	Wide SO	±2 LSB
MX7538KEWG	-40°C to +85°C	Wide SO	±1 LSB

Functional Diagram



Pin Configuration



MIXLM

Maxim Integrated Products



Call toll free 1-800-998-8800 for free samples or literature.

⁽Ordering Information continued on page 9.)
All devices — 24 lead packages
PLCC — 28 lead package
**Maxim reserves the right to ship Ceramic SB in lieu of CERDIP packages.

ABSOLUTE MAXIMUM RATINGS

VDD to DGND −0.3V, +17V VSS to AGND −15V, +0.3V VREF to AGND ±25V VRFB to AGND ±25V Digital Input Voltage to DGND −0.3V, VDD VIOUT to DGND −0.3V, VDD AGND to DGND −0.3V, VDD Power Dissipation (any Package) T0 +75°C 1000mW Derates above +75°C by 10mW°C	Operating Temperature Range 0°C to +70°C MX7538J/K 0°C to +70°C MX7538A/B -25°C to +85°C MX7538AE/BE -40°C to +85°C MX7538S/T -55°C to +125°C Storage Temperature -65°C to +150°C Lead Temperature (Soldering 10 sec) +300°C
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Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS(VDD = +11.4V to +15.75V (Note 1), V_{REF} = +10V, V_{IOUT} = V_{AGND} = V_{SS} = '0V, T_A = T_{MIN} to T_{MAX} unless otherwise noted).

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DC ACCURACY		•					•
Resolution				14			Bits
Relative Accuracy		MX7538K/B/T MX7538J/A/S				±1 ±2	LSB
Differential Nonlinearity		Guaranteed monotonic to over temperature	o 14 bits			±1	
		All	T _A = +25°C			±4	
Full Scale Error (Note 2)		MX7538J/K MX7538A/B MX7538S MX7538T	TA = T _{MIN} to T _{MAX}			±8 ±5 ±10 ±6	LSB
Gain Temperature Coefficient ∆ Gain/∆ Temperature					±2		ppm/°C
1 0 4-1		All	T _A = +25°C			±5	nA
I _{OUT} Output Leakage Current	ILKG	V _{SS} = 0V				±25	
(Note 3)	, ckg	MX7538J/K/A/B MX7538S/T	$T_A = T_{MIN}$ to T_{MAX} $T_A = T_{MIN}$ to T_{MAX}			±150	nA
REFERENCE INPUT							
V _{REF} Input Resistance	R _{REF}			3.5	6	10	kΩ
DIGITAL INPUTS							
Logic HIGH Threshold	VINH			+2.4			V
Logic LOW Threshold	V _{INL}					+0.8	V
Input Leakage Current		Digital inputs = 0V or V _{DD}	T _A = +25°C T _A = T _{MIN} to T _{MAX}			±1 ±10	μΑ
Input Capacitance (Note 4)	C _{IN}					7	pF

ELECTRICAL CHARACTERISTICS (continued)
(VDD = +11.4V to +15.75V (Note 1), VREF = +10V, VIOUT = VAGND = VSS = -300mV, TA = TMIN to TMAX unless otherwise noted).

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS	
POWER REQUIREMENTS								
Positive Supply Range	V _{DD}	Operating Range	Operating Range			+15.75	v	
rositive Supply hange	V DD	Functional with degraded	Functional with degraded specifications				1 "	
Negative Supply Range	Vss	Operating Range		-200		-500	mV	
Power Supply Current	IDD	Digital Inputs = VINH or V	INL			4	mA	
rower supply current	ם פיי	Digital Inputs = 0V or VDI)			500	μA	
TIMING CHARACTERISTICS	(See Figure,1	for timing diagram.)						
CS to WR Setup Time	t ₁			0			ns	
CS to WR Hold Time	t ₂			0			ns	
		All	T _A = +25°C	170		·.		
LDAC Pulse Width	t ₃	MX7538J/K/A/B MX7538S/T	T _A = T _{MIN} to T _{MAX} T _A = T _{MIN} to T _{MAX}	200 240			ns	
		All	T _A = +25°C	170				
Write Pulse Width	t ₄	MX7538J/K/A/B MX7538S/T	T _A = T _{MIN} to T _{MAX} T _A = T _{MIN} to T _{MAX}	200 240			ns	
		All	T _A = +25°C	140				
Data Setup Time	t ₅	MX7538J/K/A/B MX7538S/T	T _A = T _{MIN} to T _{MAX} T _A = T _{MIN} to T _{MAX}	160 180			ns	
		All	T _A = +25°C	- 20				
Data Hold Time	t ₆	MX7538J/K/A/B MX7538S/T	T _A = T _{MIN} to T _{MAX} T _A = T _{MIN} to T _{MAX}	20 30			ns	
DYNAMIC PERFORMANCE	(Note 5)							
Output Current Settling Time		T _A = +25°C To ±0.003% of full scale l _{OUT} load = 100Ω C _{EXT} alternately loaded with a	= 13pF. DAC register		0.8	1.5	μs	
Digital to Analog Glitch Impulse		Measured with V _{REF} = 0V C _{EXT} = 13pF. DAC registe with all 1s and all 0s.			20		nV-sec	
Multiplying Feedthrough Error		V _{REF} = ±10V, 10KHz sine wave. DAC register loaded with all 0s.	T _A = +25°C T _A = T _{MIN} to T _{MAX}		3 5		mVp-r	
Power Supply Rejection Δ G/ Δ V _{DD}		Δ V _{DD} = ±5%	T _A = +25°C T _A = T _{MIN} to T _{MAX}			±0.01 ±0.02	%/%	
I Output Consoltance	C	DAC Register loaded wit	h all 1s			260		
I _{OUT} Output Capacitance	Соит	DAC Register loaded wit	th all 0s			130	pF	
Output Noise Voltage Density (10Hz-100KHz)		Measured between R _{FB} a	Measured between R _{FB} and I _{OUT}		15		nV√H	

Note 1: Specifications are guaranteed for V_{DD} of +11.4V to +15.75V. At V_{DD} of 5V device is still functional with degraded specifications.

Note 2: Measured with internal R_{FB} includes effects of leakage current and gain tempco. Note 3: DAC register loaded with all 0s.

Note 4: Guaranteed by design.

Note 5: These characteristics are provided for design guidance only and are not subject to test.

Pin Description

PIN#	NAME	FUNCTION
1	V _{REF}	Voltage Reference Input
2	R _{FB}	Feedback Resistor. Used to close the loop around an external op amp.
3	lout	Current Output
4	AGND	Analog Ground. Reference point for external circuitry. This pin should carry minimum current.
5	DGND	Digital Ground
6-19	DB13-DB0	Data Inputs. DB13 (MSB), DB0 (LSB).
20	LDAC	Asynchronous Load-DAC Control Input. Active Low.
21	CS	Chip Select Control Input. Active Low.
22	WR	Write Control Input. Active Low.
23	V _{DD}	Positive Supply Voltage Input. +12V to +15V, ±5% tolerance.
24	V _{SS}	Negative Supply Voltage Input. Bias pin for high temperature, low leakage configuration. To implement a low leakage system, this pin should be at a negative voltage. Otherwise, it can be connected to the AGND pin. See Figures 4 and 5 for the recommended circuitry.

Detailed Description D/A Section

As shown in Figure 2, the basic MX7538 D/A section consists of an 11-bit R-2R resistor array, a 3-bit segmented resistor array, and NMOS current switches. The three MSBs of the digital input are decoded to drive switches A-G of the segmented array, and the remaining 11 bits drive switches S0-S10 of the R-2R array.

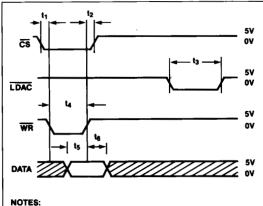
7/8th of the input current flows through the segmented resistors, and the remaining 1/8th flows through the R-2R resistor network. Switches A-G steer equally weighted currents to either AGND or IOUT, depending on the three MSBs of the digital input, and switches S0-S10 steer binarily weighted currents to either AGND or IOUT, depending on the 11 LSBs of the digital input. The input resistance at VREF is constant, therefore, it can be driven by a voltage or current source of positive or negative polarity.

The MX7538 is optimized for unipolar output operation (analog output from 0 to -VREF) although bipolar operation (analog output from +VREF to -VREF) is possible with additional components (see Figure 5).

Logic Input Truth Table

Eogic input train table							
CS	LDAC	WR	FUNCTION				
0	1	0	Load Input Register				
1	0	×	Load DAC Register from Input Register				
0	0	0	Input and DAC Registers are transparent				
1	1	Х	No operation				
Х	1	1	No operation				

Note: X = Don't Care



- NOTES:

 1. ALL INPUT SIGNAL RISE AND FALL TIMES MEASURE FROM 10% TO 90% OF +5V, t_r = t_f = 20ns.
- 2. TIMING MEASUREMENT REFERENCE LEVEL IS VIH +VIL
- IF LDAC IS ACTIVATED PRIOR TO THE RISING EDGE OF WR, THEN IT MUST STAY LOW FOR to or LONGER AFTER WR GOES HIGH.

Figure 1. MX7538 Timing Diagram

The equivalent circuit for the analog portion of the DAC is shown in Figure 3. Cout varies from about 90 to 180pF depending on the digital code. Ro, the equivalent output resistance of the DAC, also varies with input code. g(V_{REF},N) is the Thevenin equivalent voltage generator due to the reference input voltage, V_{REF}, and the transfer function of the R-2R ladder, N.

Digital Section

All digital inputs are both TTL and 5V CMOS logic compatible, with typical input currents of less than 1nA. Further, digital inputs are protected against electrostatic discharge (ESD). To minimize power supply current high and low logic levels (V_{INH} and V_{INL}) digital input voltages should be kept close to 5V and 0V, respectively.

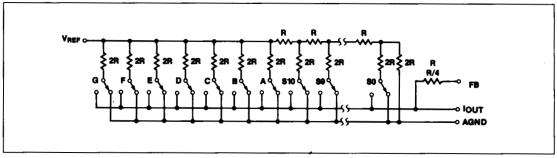


Figure 2. Simplified Circuit Diagram for the MX7538 D/A Section

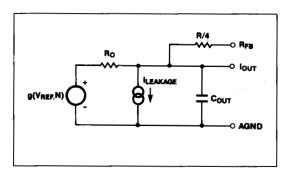


Figure 3. MX7538 Equivalent Analog Output Circuit

Application Information Unipolar Operation (2-Quadrant Multiplication)

Figure 4 shows the circuit diagram for unipolar binary operation. With an AC input, the circuit performs 2-quadrant multiplication. The code table for Figure 4 is given in Table 1.

Capacitor C1 provides phase compensation and helps prevent overshoot and ringing when high speed op amps are used. Note that the polarity of the output is the inverse of the reference input.

Typical connections for unipolar operation are shown in Figure 4. R3 and R4 are included for gain adjustment. However, if precision exceeding that specified in the Electrical Characteristics is not required, R3 and R4 may be omitted.

Offset Error Adjustment

- 1. Load DAC register with all 0s.
- Adjust offset of amplifier A1 so that V_{OUT} is at a minimum (i.e., ≤ 30μV).

Gain Error Adjustment

- 1. Load DAC register with all 1s.
- Trim potentiometer, R3, so that V_{OUT} = -V_{IN} (16383/16384).

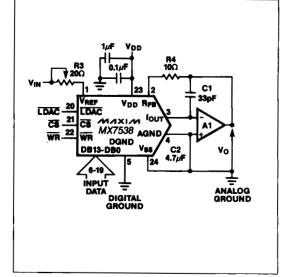


Figure 4. Unipolar Binary Operation

Table 1. Unipolar Binary Code

BINARY NUM MSB	BER LSB	ANALOG OUTPUT				
11 1111 1111	1111	-VIN (16383)				
10 0000 0000	0000	$-V_{IN}\left(\frac{8192}{16384}\right) = -1/2 V_{IN}$				
00 0000 0000	0001	-VIN (1/16384)				
00 0000 0000	0000	ov				

In fixed reference applications, full scale can also be adjusted by omitting R3 and R4 and trimming the reference voltage magnitude. In many applications, the excellent Gain Tempco and Gain Error specifications eliminate the need for gain adjustment. However, if trim resistors are required and the DAC is to operate over a wide temperature range, low tempco (<300ppm/°C) resistors must be used.

Bipolar Operation (4-Quadrant Multiplication)

Bipolar, or 4-quadrant operation, is shown in Figure 5. This configuration uses offset binary coding. With the DAC loaded to 10 0000 0000 0000, adjust R3 for $V_{OUT} = 0V$. Alternatively, one can omit R3 and R4 and adjust the ratio of R7 and R8 for $V_{OUT} = 0V$. Full scale trimming is done by adjusting the amplitude of V_{IN} or by varying the value of R9.

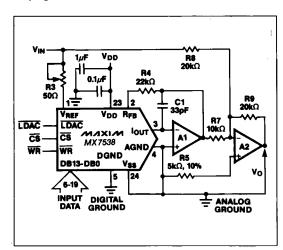


Figure 5. Bipolar Operation

Table 2. Bipolar Code for Offset Binary

BINAR MSB	Y NUM	BER LSB	ANALOG OUTPUT
11 1111	1111.	1111	+VIN (8191)
10 0000	0000	0001	$+VIN\left(\frac{1}{8192}\right)$
10 0000	0000	0000	0
01 1111	1111	1111	$-V_{IN}\left(\frac{1}{8192}\right)$
00 0000	0000	0000	-VIN (8192)

Resistors R7, R8, R9 must be matched to 0.003%. Mismatching of R7 and R8 causes both offset and full scale errors. For wide temperature range operation, resistors should be of the same material so that their temperature coefficients match and track.

Table 2 shows the Offset Binary Code obtained with the circuit of Figure 5. Note that by inverting the MSB of the DAC, a 2's Complement transfer function is obtained.

Grounding Considerations

Since l_{OUT} and the output amplifier's noninverting input are sensitive to offset voltages, nodes that need to be grounded should be connected directly to a "single point" ground through a separate, very low resistance path. Note that the output currents at l_{OUT} and AGND vary with input code and create code dependent errors if these terminals are connected to ground (or a virtual ground) through a resistive path.

It is important to use a proper grounding technique to obtain high accuracy.

Low Leakage Configuration

Leakage current in the DAC flowing into the $I_{\rm OUT}$ line can cause gain, linearity and offset errors. Leakage is worse at high temperatures.

Dynamic Considerations

In static or DC applications, the AC characteristics of the output amplifier are not critical. In higher speed applications, where either the reference input is an AC signal or the DAC output must quickly settle to a new programmed value, the AC parameters of the output op amp must be considered.

Another error source in dynamic applications is parasitic coupling of signals from the $V_{\rm REF}$ terminal to $I_{\rm OUT}.$ This coupling is normally caused by board layout and lead-to-lead package capacitance. Signals can also be injected into the DAC outputs when the digital inputs are switched. This digital feedthrough is mostly dependent on circuit board layout and on-chip capacitive coupling. Layout induced feedthrough can be minimized with guard traces between digital inputs, $V_{\rm REF},$ and the DAC outputs.

Digital Feedthrough

In the microprocessor interface diagrams shown in Figures 6-8, the digital inputs of the DAC are directly connected to the microprocessor bus. Even when the device is not selected, activity on the bus can feed through on the DAC output through package capacitance and show up as noise. This can be minimized by isolating the DAC from the digital bus as shown in Figure 9.

Compensation

A compensation capacitor, C1, may be needed when the DAC is used with a high speed output amplifier. The purpose of the capacitor is to cancel the pole formed by the DAC's output capacitance and internal feedback resistance. Its value depends on the type of op ampused but typical values range from 10 to 33pF. Too small a value causes output ringing while excess capacitance overdamps the output. The size of C1 can be minimized, and output settling performance improved, by keeping the PC board traces short and keeping stray capacitance at I_{OUT} as small as possible.

Bypessing

A 1 μ F bypass capacitor, in parallel with a 0.1 μ F ceramic cap, should be connected as close to the DAC's V_{DD} and GND pins as possible. High frequency noise rejection is optimized if tantalum is used for the 1 μ F capacitor. A V_{SS} decoupling capacitor of 4.7 μ F is also required if a low leakage configuration is desired.

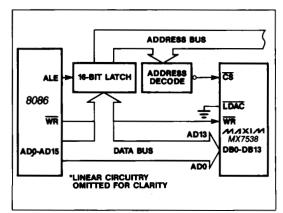


Figure 6. MX7538 - 8086 Interface Circuit

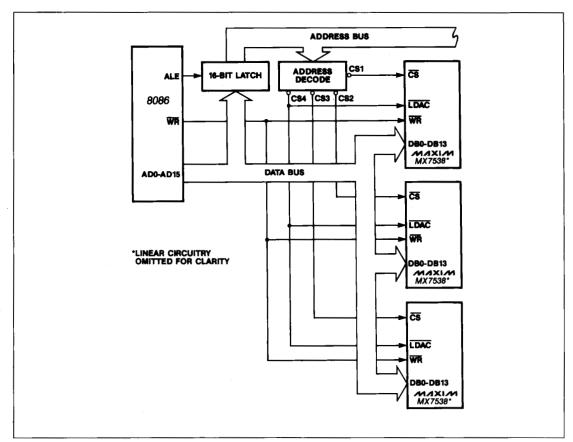


Figure 7. MX7538 - 8086 Interface: Multiple DAC System

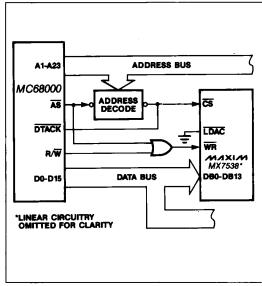


Figure 8. MX7538 - MC6800 Interface

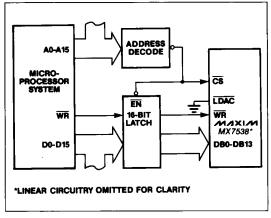


Figure 9. MX7538 Interface Circuit Using Latches to Minimize-Digital Feedthrough

The MX7538 has high-impedance digital inputs. To minimize noise pick-up, they should be connected to either V_{DD} or GND terminals when not used. It is also good practice to connect active inputs to V_{DD} or GND through high valued resistors (1M Ω) to prevent static charge accumulation if these pins are left floating, as might be the case when a circuit card is left unconnected.

Op Amp Selection

Input offset voltage (V_{OS}), input bias current (I_B) and offset voltage drift ($TC\ V_{OS}$) are key parameters determining choice of a suitable amplifier (see Table 3). To maintain specified accuracy with V_{REF} of 10V, V_{OS} should be less than 30 μ V, and I_B should be less than 2nA. Open loop gain should be greater than 340,000. Maxim's MAX400 has low $V_{OS}(10\mu V\ max)$, low $I_B(2nA)$ and low $TC\ V_{OS}(0.3\mu V)^{\circ}C\ max)$. This op amp can be used without adjustments. For medium frequency applications the OP-27 is suggested and for even higher frequency applications the HA 2620 is recommended. Note however, these op amps require external offset adjustment.

_ Microprocessor Interfacing MaximMX7538 to 8086A Interface

Figure 6 shows the 8086 16-bit microprocessor interfacing to a single MX7538. In this setup the double buffering feature of the DAC is not used. AD13-AD0 of the 16-bit data bus are connected to the DAC data bus (DB13-DB0). The 14-bit word is written to the DAC in one MOV instruction, and the analog output responds immediately. In this example the DAC address is D000. A software routine for Figure 6 is given in Table 4.

In a multiple DAC system, the double buffering of the DAC chips allows the user to simultaneously update all DACs. In Figure 7, a 14-bit word is loaded into the Input Registers of each of the DACs in sequence. Then, with one instruction to the appropriate address, CS4 (i.e., LDAC) is brought low, updating all the DACs simultaneously.

MX7538 to MC68000 Interface

Figure 8 shows the MX7538 interfaced with the MC68000. The following routine in Table 5 inputs data to the MX7538 from the MC68000. First, data is written to the DAC Input Registers, then data is output via the DAC Register.

Table 3. Op Amp Selection

.anic c. op .anip co	and at all truth accounts									
OP AMP	INPUT OFFSET VOLTAGE (V _{OS})	INPUT BIAS CURRENT (IB)	OFFSET VOLTAGE DRIFT (TC Vos)	SETTLING TO 0.003% FS						
MAX400	10μV	2nA	0.3μV/° C	50µs						
Maxim OP-07	25μV	2nA	0.6μV/°C	50µs						
AD544L*	500μV	25pA	5μV/° C	5μs						
HA2620*	4mV	35nA	20μV/°C	0.8µs						

^{*}AD544L is an Analog Devices part, HA2620 is a Harris Semiconductor part.

Table 4. Loading MX7538 from an 8086

	ASSUME DS:DACLOAD, CS:DACLOAD DACLOAD SEGMENT AT 000								
00	00 8CC9 MOV CX,CS :DEFINE DATA SEGMENT REGISTER EQUAL								
02	8ED9	MOVDS,CX	:TO CODES SEGMENT REGISTER						
04	BF00D0	MOVDI,#D000	:LOAD DI WITH D000						
07	C705"YZWX"	MOV MEM,#YZWX	:DAC LOADED WITH WXYZ						
0B	EA0000		:CONTROL IS RETURNED TO THE						
0E	00FF		MONITOR PROGRAM						

Table 5. Loading MX7538 from a 68000

01000	MOVE.W	#W,D0	The desired DAC data, W, is loaded into Data Register 0.					
	MOVE.W	D0,\$E000	The Data W is transferred between D0 and DAC register.					
	MOVE.B	#228,D7	Control returned to the System Monitor Program.					
	TRAP	#14						

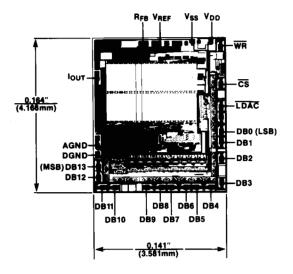
Ordering Information (continued)

PART	TEMP. RANGE	PACKAGE*	ERROR
MX7538AQ	-25°C to + 85°C	CERDIP**	±2 LSB
MX7538BQ	-25°C to +85°C	CERDIP**	±1 LSB
MX7538AD	-25°C to +85°C	Ceramic SB	±2 LSB
MX7538BD	-25°C to +85°C	Ceramic SB	±1 LSB
MX7538SQ	-55°C to +125°C	CERDIP**	±2 LSB
MX7538TQ	-55°C to +125°C	CERDIP**	±1 LSB
MX7538SD	-55°C to +125°C	Ceramic SB	±2 LSB
MX7538TD	-55°C to +125°C	Ceramic SB	±1 LSB

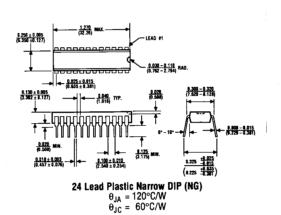
- * All devices 24 lead packages
- PLCC 28 lead package

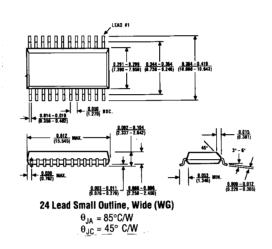
 ** Maxim reserves the right to ship Ceramic SB in lieu of
 CERDIP packages.

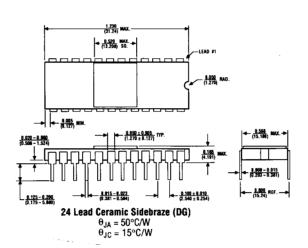
Chip Topography



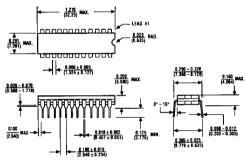
Package Information



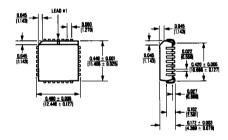




Package Information (continued)



24 Lead Narrow CERDIP (RG) $\theta_{JA}=80^{\circ}\text{C/W}$ $\theta_{JC}=40^{\circ}\text{C/W}$



28 Lead Plastic Chip Carrier (Quad Pak) (QI) $\theta_{JA} = 100^{\circ} C/W \\ \theta_{JC} = 45^{\circ} C/W$